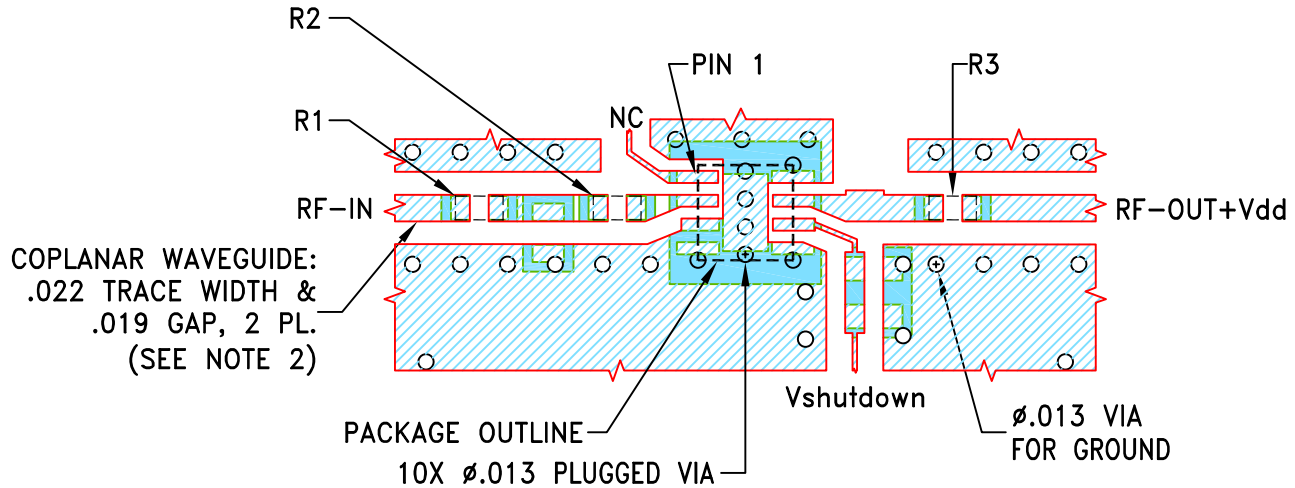


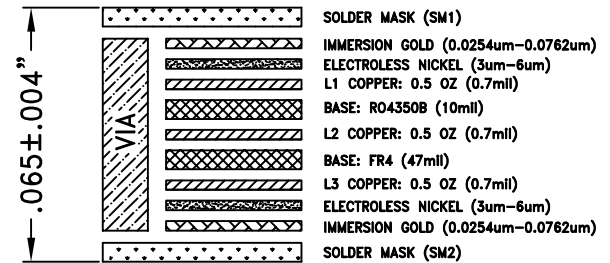
REVISIONS					
REV	ECN No.	DESCRIPTION	DATE	DR	AUTH
OR	ECO-024615	NEW RELEASE	03/15/25	ITG	IL

SUGGESTED MOUNTING CONFIGURATION
FOR MC1631-1 CASE STYLE



COMPONENT	SIZE
R1-R3	0402

3 LAYER STACK-UP DETAIL

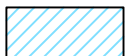


NOTES:

1. PCB IS MULTILAYER PCB, SEE STACK-UP DIAGRAM.
2. TRACE WIDTH & GAP ARE SHOWN FOR ROGERS RO4350B WITH DIELECTRIC THICKNESS .010".
COPPER: 1/2 OZ. EACH LAYER. FOR OTHER MATERIALS TRACE WIDTH & GAP MAY NEED TO BE MODIFIED.
3. CHIP COMPONENT FOOT PRINTS SHOWN FOR REFERENCE, FOR COMPONENT VALUES REFER TO TB-TSS-23ULNC+.
4. LAYERS 2 & 3 OF PCB ARE CONTINUOUS GROUND PLANE.
5. UNIT LAND PATTERN WAS OPTIMIZED FOR BETTER PERFORMANCE.



DENOTES PCB COPPER LAYOUT WITH SMOBC (SOLDER MASK OVER BARE COPPER).



DENOTES COPPER LAND PATTERN FREE OF SOLDER MASK.

UNLESS OTHERWISE SPECIFIED	INITIALS		DATE
DIMENSIONS ARE IN INCHES TOLERANCES ON: 2 PL DECIMALS ± 3 PL DECIMALS ± .005 ANGLES ± FRACTIONS ±	DRAWN	ITG	02/25/25
	CHECKED	GF	02/25/25
	APPROVED	IL	02/25/25

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Brooklyn NY 11235

PL, MC1631-1, TB-TSS-23ULNC+

SIZE	CODE IDENT	DRAWING NO:	REV:
A	15542	98-PL-815	OR
FILE:	98PL815	SCALE: 6:1	SHEET: 1 OF 1